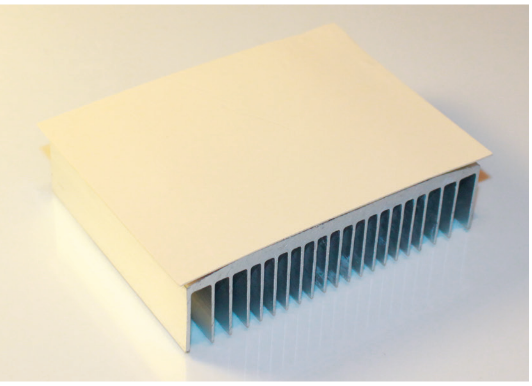
L37-3L
Low Bleed Thermal Pad



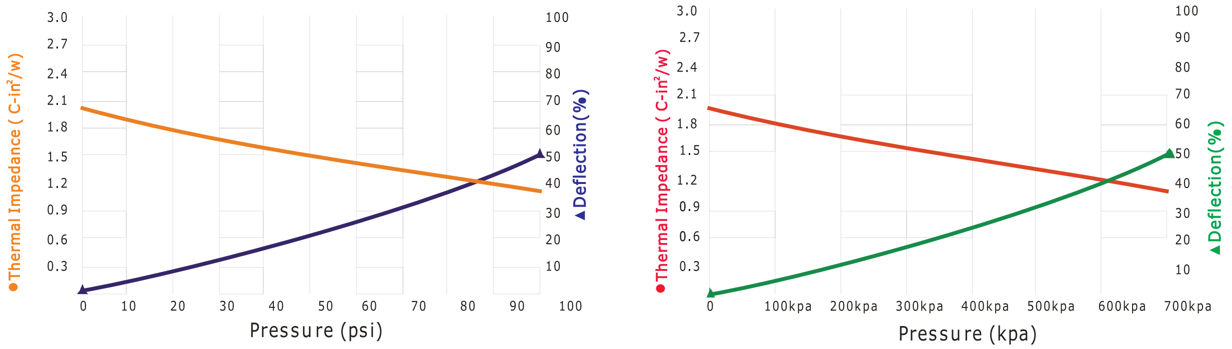
Features

Low bleed
High insulation strength
Long term stability
Low thermal resistance

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device / Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

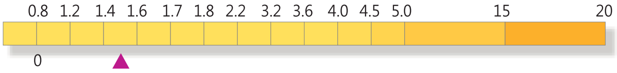
Thermal Resistance V.S Pressure V.S Deflection



Properties

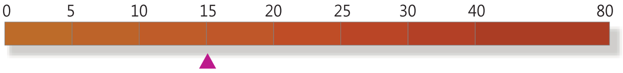
⬢ REACH Compliant
⬢ RoHS Compliant

Thermal Conductivity: 1.5 W/mK
(W/mK - Z Axis)



Testing sample thickness:1.0 mm

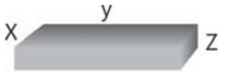
Hardness: 15 (Shore A)
(Shore A)



In the thermal resistance vs pressure vs deflection charts L37-3L provides low thermal impedance.
As the pressure increases the thermal impedance decreases. L37-3L provides good compliance and softness.

Property	L37-3L	Unit	Test Method
Colour	Yellow	-	Visual
Thickness (Available thickness range)	0.5 - 10	mm	ASTM D374
	0.0197 - 0.3937	inch	ASTM D374
Optimal Temperature Range	-45 to 200	˚C	-
Density	2.4	g/cm³	ASTM D792
Thermal Conductivity	1.5	W/mK	ASTM D5470
Hardness	15	Shore A	ASTM D2240
Thermal Resistance			
T=1.0mm 10psi	2	K-in²/W	ASTM D5470
T=1.0mm 50psi	1.5	K-in²/W	ASTM D5470
T=1.0mm 100psi	1	K-in²/W	ASTM D5470
Percent Deflection			
T=1.0mm 10psi	5	%	ASTM D575
T=1.0mm 50psi	20	%	ASTM D575
T=1.0mm 100psi	50	%	ASTM D575
Breakdown Voltage	15	kV/mm	ASTM D149
TML	‹0.2	%	ASTM E595
Tensile Strength	1	Kgf/cm²	ASTM D412
Elongation	300	%	ASTM D412

Available with an
adhesive backing



X y z
L37-3L - 15 - 20 - 3 - 0A, 20 3
1 2

1. Part Number
2. Size X-Y-Z
3. Quantity